Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.076”**

**ANODE**

**.053 x .053”**

**.076”**

**Top Material: Al**

**Backside Material: TiNiAg**

**Bond Pad Size: .053 x .053”**

**Backside Potential: CATHODE**

**APPROVED BY: DK DIE SIZE .076” X .076” DATE: 11/10/21**

**MFG: SILICON SUPPLIES THICKNESS .010” P/N: 1N5811**

**DG 10.1.2**

#### Rev B, 7/1